# **Quad Analog Switch/ Multiplexer/Demultiplexer**

# **High-Performance Silicon-Gate CMOS**

The MC74HC4066A utilizes silicon-gate CMOS technology to achieve fast propagation delays, low ON resistances, and low OFF-channel leakage current. This bilateral switch/multiplexer/demultiplexer controls analog and digital voltages that may vary across the full power-supply range (from  $V_{\rm CC}$  to GND).

The HC4066A is identical in pinout to the metal–gate CMOS MC14016 and MC14066. Each device has four independent switches. The device has been designed so the ON resistances ( $R_{ON}$ ) are more linear over input voltage than  $R_{ON}$  of metal–gate CMOS analog switches.

The ON/OFF control inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs. For analog switches with voltage-level translators, see the HC4316A.

#### **Features**

- Fast Switching and Propagation Speeds
- High ON/OFF Output Voltage Ratio
- Low Crosstalk Between Switches
- Diode Protection on All Inputs/Outputs
- Wide Power-Supply Voltage Range ( $V_{CC}$  GND) = 2.0 to 12.0 V
- Analog Input Voltage Range ( $V_{CC}$  GND) = 2.0 to 12.0 V
- Improved Linearity and Lower ON Resistance over Input Voltage than the MC14016 or MC14066
- Low Noise
- Chip Complexity: 44 FETs or 11 Equivalent Gates
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable



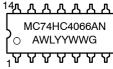
#### ON Semiconductor®

http://onsemi.com

MARKING DIAGRAMS

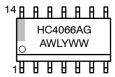


PDIP-14 N SUFFIX CASE 646





SOIC-14 D SUFFIX CASE 751A





TSSOP-14 DT SUFFIX CASE 948G



A = Assembly Location

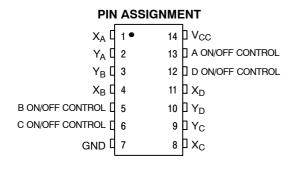
WL, L = Wafer Lot YY, Y = Year WW, W = Work Week

(Note: Microdot may be in either location)

= Pb-Free Package

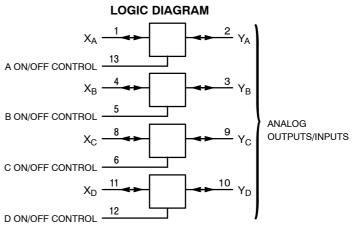
#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.



#### **FUNCTION TABLE**

On/Off Control Input	State of Analog Switch
L	Off
Н	On



ANALOG INPUTS/OUTPUTS =  $X_A$ ,  $X_B$ ,  $X_C$ ,  $X_D$  PIN 14 =  $V_{CC}$  PIN 7 = GND

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC74HC4066ANG	PDIP-14 (Pb-Free)	25 Units / Rail
MC74HC4066ADG	SOIC-14 (Pb-Free)	55 Units / Rail
MC74HC4066ADR2G	SOIC-14 (Pb-Free)	2500 / Tape & Reel
MC74HC4066ADTR2G	TSSOP-14 (Pb-Free)	2500 / Tape & Reel
NLVHC4066ADTR2G	TSSOP-14 (Pb-Free)	2500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

#### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	Positive DC Supply Voltage (Referenced to GND)	- 0.5 to + 14.0	V
V <sub>IS</sub>	Analog Input Voltage (Referenced to GND)	$-0.5$ to $V_{CC}$ + 0.5	V
V <sub>in</sub>	Digital Input Voltage (Referenced to GND)	$-0.5$ to $V_{CC}$ + 0.5	V
- 1	DC Current Into or Out of Any Pin	± 25	mA
P <sub>D</sub>	Power Dissipation in Still Air, Plastic DIP† EIAJ/SOIC Package† TSSOP Package†	750 500 450	mW
T <sub>stg</sub>	Storage Temperature	- 65 to + 150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP, SOIC or TSSOP Package)	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

†Derating Plastic DIP: - 10 mW/°C from 65° to 125°C EIAJ/SOIC Package: - 7 mW/°C from 65° to 125°C

TSSOP Package: - 6.1 mW/°C from 65° to 125°C

#### This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, $V_{\text{in}}$ and Vout should be constrained to the range GND $\leq$ (V<sub>in</sub> or V<sub>out</sub>) $\leq$ V<sub>CC</sub>.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or  $V_{CC}$ ). Unused outputs must be left open. I/O pins must be connected to a properly terminated line or bus.

#### RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	Positive DC Supply Voltage (Referenced to GND)	2.0	12.0	V
V <sub>IS</sub>	Analog Input Voltage (Referenced to GND)	GND	V <sub>CC</sub>	V
V <sub>in</sub>	Digital Input Voltage (Referenced to GND)	GND	V <sub>CC</sub>	V
V <sub>IO</sub> *	Static or Dynamic Voltage Across Switch	-	1.2	V
T <sub>A</sub>	Operating Temperature, All Package Types	<b>–</b> 55	+ 125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time, ON/OFF Control Inputs (Figure 10) $V_{CC} = 2.0 \text{ V} \\ V_{CC} = 3.0 \text{ V} \\ V_{CC} = 4.5 \text{ V} \\ V_{CC} = 9.0 \text{ V} \\ V_{CC} = 12.0 \text{ V}$	0 0 0 0	1000 600 500 400 250	ns

<sup>\*</sup>For voltage drops across the switch greater than 1.2 V (switch on), excessive  $V_{CC}$  current may be drawn; i.e., the current out of the switch may contain both  $V_{CC}$  and switch input components. The reliability of the device will be unaffected unless the Maximum Ratings are exceeded.

#### DC ELECTRICAL CHARACTERISTIC Digital Section (Voltages Referenced to GND)

				Guaranteed Li		mit	
Symbol	Parameter	Test Conditions	v <sub>cc</sub> v	– 55 to 25°C	≤ <b>85</b> °C	≤ 125°C	Unit
V <sub>IH</sub>	Minimum High-Level Voltage ON/OFF Control Inputs	R <sub>on</sub> = Per Spec	2.0 3.0 4.5 9.0 12.0	1.5 2.1 3.15 6.3 8.4	1.5 2.1 3.15 6.3 8.4	1.5 2.1 3.15 6.3 8.4	V
V <sub>IL</sub>	Maximum Low-Level Voltage ON/OFF Control Inputs	R <sub>on</sub> = Per Spec	2.0 3.0 4.5 9.0 12.0	0.5 0.9 1.35 2.7 3.6	0.5 0.9 1.35 2.7 3.6	0.5 0.9 1.35 2.7 3.6	V
I <sub>in</sub>	Maximum Input Leakage Current ON/OFF Control Inputs	V <sub>in</sub> = V <sub>CC</sub> or GND	12.0	± 0.1	± 1.0	± 1.0	μΑ
I <sub>CC</sub>	Maximum Quiescent Supply Current (per Package)	V <sub>in</sub> = V <sub>CC</sub> or GND V <sub>IO</sub> = 0 V	6.0 12.0	2 4	20 40	40 160	μΑ

#### DC ELECTRICAL CHARACTERISTICS Analog Section (Voltages Referenced to GND)

				Gu	aranteed Li	mit	
Symbol	Parameter	Test Conditions	V <sub>CC</sub> V	– 55 to 25°C	≤ <b>85</b> °C	≤ 125°C	Unit
R <sub>on</sub>	Maximum "ON" Resistance	$\begin{aligned} &V_{in} = V_{IH} \\ &V_{IS} = V_{CC} \text{ to GND} \\ &I_{S} \leq 2.0 \text{ mA (Figures 1, 2)} \end{aligned}$	2.0† 3.0† 4.5 9.0 12.0	- 120 70 70	- 160 85 85	- 200 100 100	Ω
		$\begin{split} &V_{in} = V_{IH} \\ &V_{IS} = V_{CC} \text{ or GND} \\ &(\text{Endpoints}) \\ &I_{S} \leq 2.0 \text{ mA (Figures 1, 2)} \end{split}$	2.0 3.0 4.5 9.0 12.0	- - 70 50 50	- - 85 60 60	- - 120 80 80	
ΔR <sub>on</sub>	Maximum Difference in "ON" Resistance Between Any Two Channels in the Same Package	$\begin{aligned} &V_{in} = V_{IH} \\ &V_{IS} = 1/2 \; (V_{CC} - GND) \\ &I_{S} \leq 2.0 \; mA \end{aligned}$	2.0 4.5 9.0 12.0	- 20 15 15	- 25 20 20	- 30 25 25	Ω
l <sub>off</sub>	Maximum Off-Channel Leakage Current, Any One Channel	$V_{in} = V_{IL}$ $V_{IO} = V_{CC}$ or GND Switch Off (Figure 3)	12.0	0.1	0.5	1.0	μΑ
l <sub>on</sub>	Maximum On-Channel Leakage Current, Any One Channel	$V_{in} = V_{IH}$ $V_{IS} = V_{CC}$ or GND (Figure 4)	12.0	0.1	0.5	1.0	μΑ

<sup>†</sup>At supply voltage (V<sub>CC</sub>) approaching 3 V the analog switch-on resistance becomes extremely non-linear. Therefore, for low-voltage operation, it is recommended that these devices only be used to control digital signals.

## $\textbf{AC ELECTRICAL CHARACTERISTICS} \ (C_L = 50 \ \text{pF, ON/OFF Control Inputs:} \ t_r = t_f = 6 \ \text{ns})$

			Gu	Guaranteed Limit		
Symbol	Parameter	V <sub>CC</sub> V	– 55 to 25°C	≤ <b>85</b> °C	≤ 125°C	Unit
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Analog Input to Analog Output (Figures 8 and 9)	2.0 3.0 4.5 9.0 12.0	40 30 10 10	50 40 13 13	60 50 15 15	ns
t <sub>PLZ</sub> , t <sub>PHZ</sub>	Maximum Propagation Delay, ON/OFF Control to Analog Output (Figures 10 and 11)	2.0 3.0 4.5 9.0 12.0	80 60 30 25 25	90 70 38 28 28	110 80 45 30 30	ns
t <sub>PZL</sub> , t <sub>PZH</sub>	Maximum Propagation Delay, ON/OFF Control to Analog Output (Figures 10 and 1 1)		80 45 25 25 25	90 50 32 32 32	100 60 37 37 37	ns
С	Maximum Capacitance ON/OFF Control Input Control Input = GND Analog I/O Feedthrough	- - -	10 35 1.0	10 35 1.0	10 35 1.0	pF

		Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
Cpn	Power Dissipation Capacitance (Per Switch) (Figure 13)*	15	pF

<sup>\*</sup>Used to determine the no-load dynamic power consumption:  $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$ .

### ADDITIONAL APPLICATION CHARACTERISTICS (Voltages Referenced to GND Unless Noted)

Symbol	Parameter	Test Conditions	V <sub>CC</sub>	Limit* 25°C 54/74HC	Unit
BW	Maximum On–Channel Bandwidth or Minimum Frequency Response (Figure 5)		4.5 9.0 12.0	150 160 160	MHz
_	Off-Channel Feedthrough Isolation (Figure 6)	$\begin{split} f_{in} &\equiv \text{Sine Wave} \\ \text{Adjust } f_{in} &\text{ Voltage to Obtain 0 dBm at V}_{IS} \\ f_{in} &= 10 \text{ kHz}, \text{ R}_L = 600 \ \Omega, \text{ C}_L = 50 \text{ pF} \end{split}$	4.5 9.0 12.0	- 50 - 50 - 50	dB
		$f_{in}$ = 1.0 MHz, $R_L$ = 50 $\Omega$ , $C_L$ = 10 pF	4.5 9.0 12.0	- 40 - 40 - 40	
_	Feedthrough Noise, Control to Switch (Figure 7)	$\begin{split} V_{in} & \leq \text{1 MHz Square Wave } (t_f = t_f = 6 \text{ ns}) \\ \text{Adjust R}_L \text{ at Setup so that } I_S = 0 \text{ A} \\ R_L = 600 \ \Omega, \ C_L = 50 \text{ pF} \end{split}$	4.5 9.0 12.0	60 130 200	$mV_PP$
		$R_L$ = 10 kΩ, $C_L$ = 10 pF	4.5 9.0 12.0	30 65 100	
_	Crosstalk Between Any Two Switches (Figure 12)	$ \begin{aligned} f_{in} &\equiv \text{Sine Wave} \\ \text{Adjust } f_{in} &\text{ Voltage to Obtain 0 dBm at V}_{IS} \\ f_{in} &= 10 \text{ kHz}, \text{ R}_{L} = 600 \ \Omega, \text{ C}_{L} = 50 \text{ pF} \end{aligned} $	4.5 9.0 12.0	- 70 - 70 - 70	dB
		$f_{in}$ = 1.0 MHz, $R_L$ = 50 $\Omega$ , $C_L$ = 10 pF	4.5 9.0 12.0	- 80 - 80 - 80	
THD	Total Harmonic Distortion (Figure 14)	$\begin{aligned} f_{in} &= 1 \text{ kHz}, \ R_L = 10 \text{ k}\Omega, \ C_L = 50 \text{ pF} \\ \text{THD} &= \text{THD}_{Measured} - \text{THD}_{Source} \\ V_{IS} &= 4.0 \text{ Vpp sine wave} \\ V_{IS} &= 8.0 \text{ Vpp sine wave} \\ V_{IS} &= 11.0 \text{ Vpp sine wave} \end{aligned}$	4.5 9.0 12.0	0.10 0.06 0.04	%

<sup>\*</sup>Guaranteed limits not tested. Determined by design and verified by qualification.

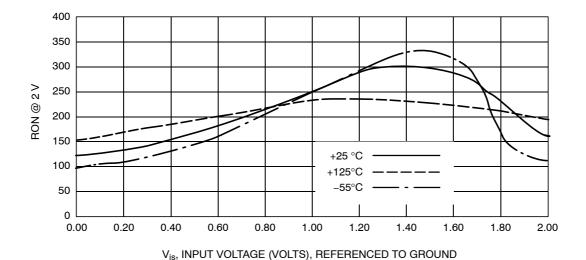


Figure 1a. Typical On Resistance,  $V_{CC} = 2.0 \text{ V}$ 

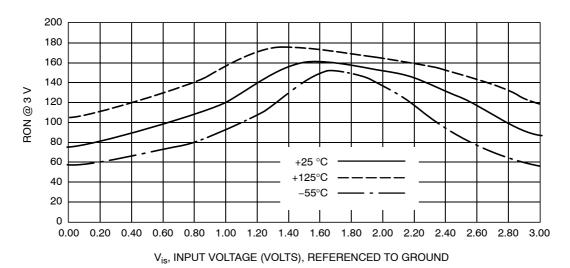


Figure 1b. Typical On Resistance, V<sub>CC</sub> = 3.0 V

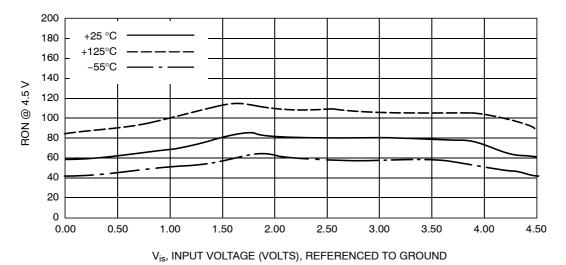
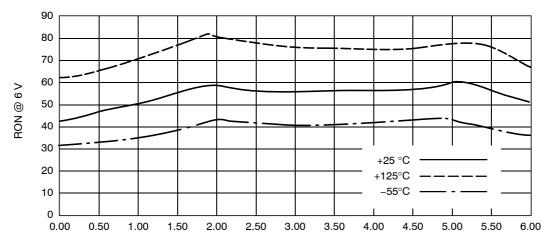


Figure 1c. Typical On Resistance, V<sub>CC</sub> = 4.5 V



V<sub>is</sub>, INPUT VOLTAGE (VOLTS), REFERENCED TO GROUND

Figure 1d. Typical On Resistance,  $V_{CC} = 6.0 \text{ V}$ 

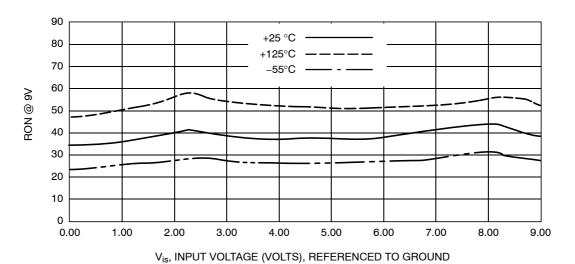


Figure 1e. Typical On Resistance, V<sub>CC</sub> = 9.0 V

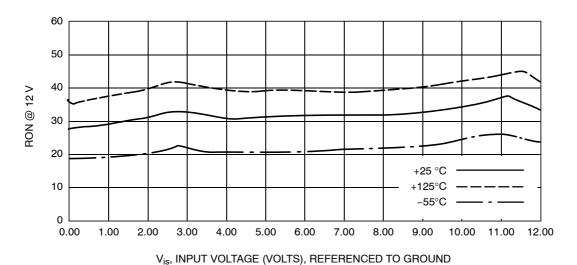


Figure 1f. Typical On Resistance, V<sub>CC</sub> = 12.0 V

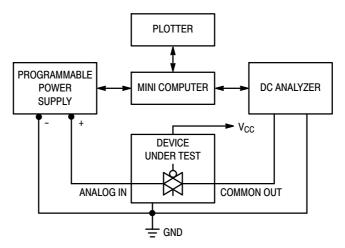


Figure 2. On Resistance Test Set-Up

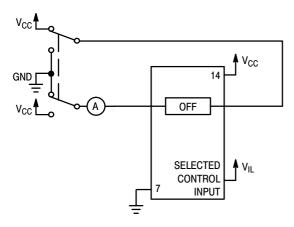


Figure 3. Maximum Off Channel Leakage Current, Any One Channel, Test Set-Up

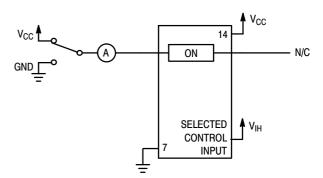
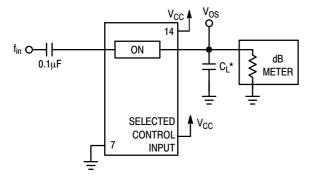
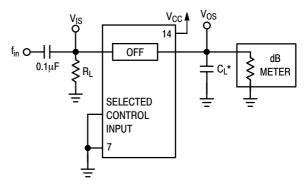


Figure 4. Maximum On Channel Leakage Current, Test Set-Up



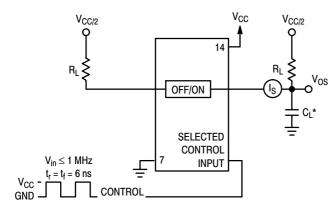
\*Includes all probe and jig capacitance.

Figure 5. Maximum On-Channel Bandwidth
Test Set-Up



\*Includes all probe and jig capacitance.

Figure 6. Off-Channel Feedthrough Isolation, Test Set-Up



\*Includes all probe and jig capacitance.

Figure 7. Feedthrough Noise, ON/OFF Control to Analog Out, Test Set-Up

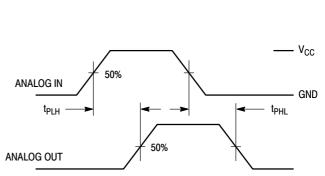
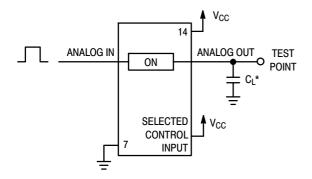
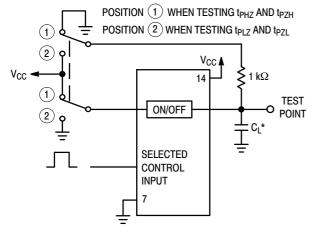


Figure 8. Propagation Delays, Analog In to Analog Out



<sup>\*</sup>Includes all probe and jig capacitance.

Figure 9. Propagation Delay Test Set-Up



<sup>\*</sup>Includes all probe and jig capacitance.

Figure 11. Propagation Delay Test Set-Up

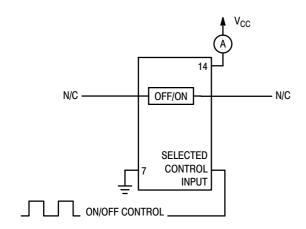


Figure 13. Power Dissipation Capacitance
Test Set-Up

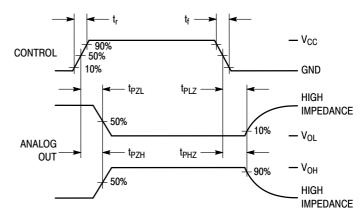
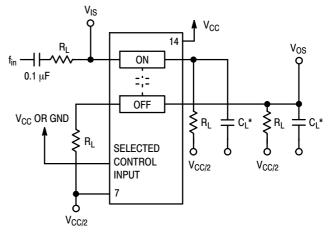
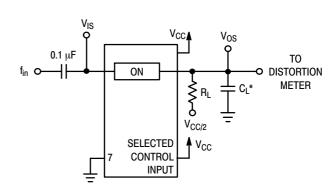


Figure 10. Propagation Delay, ON/OFF Control to Analog Out



<sup>\*</sup>Includes all probe and jig capacitance.

Figure 12. Crosstalk Between Any Two Switches, Test Set-Up



<sup>\*</sup>Includes all probe and jig capacitance.

Figure 14. Total Harmonic Distortion, Test Set-Up

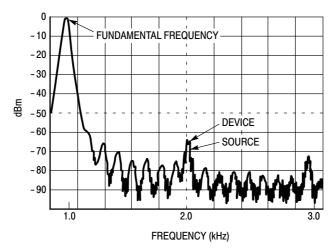


Figure 15. Plot, Harmonic Distortion

#### **APPLICATION INFORMATION**

The ON/OFF Control pins should be at  $V_{CC}$  or GND logic levels,  $V_{CC}$  being recognized as logic high and GND being recognized as a logic low. Unused analog inputs/outputs may be left floating (not connected). However, it is advisable to tie unused analog inputs and outputs to  $V_{CC}$  or GND through a low value resistor. This minimizes crosstalk and feedthrough noise that may be picked–up by the unused I/O pins.

The maximum analog voltage swings are determined by the supply voltages  $V_{CC}$  and GND. The positive peak analog voltage should not exceed  $V_{CC}$ . Similarly, the negative peak analog voltage should not go below GND. In the example

below, the difference between  $V_{\rm CC}$  and GND is twelve volts. Therefore, using the configuration in Figure 16, a maximum analog signal of twelve volts peak-to-peak can be controlled.

When voltage transients above  $V_{CC}$  and/or below GND are anticipated on the analog channels, external diodes (Dx) are recommended as shown in Figure 17. These diodes should be small signal, fast turn-on types able to absorb the maximum anticipated current surges during clipping. An alternate method would be to replace the Dx diodes with Mosorbs (Mosorb<sup>TM</sup> is an acronym for high current surge protectors). Mosorbs are fast turn-on devices ideally suited for precise DC protection with no inherent wear out mechanism.

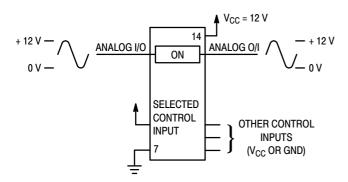


Figure 16. 12 V Application

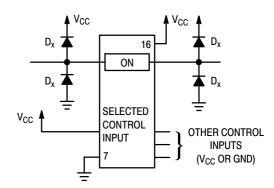


Figure 17. Transient Suppressor Application

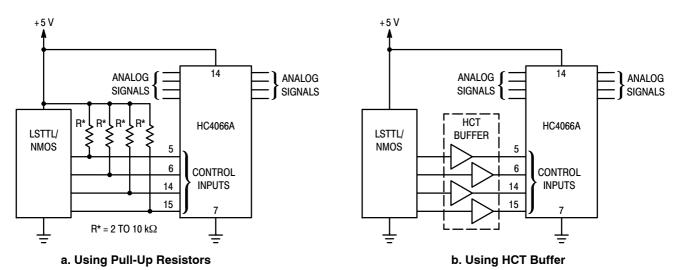


Figure 18. LSTTL/NMOS to HCMOS Interface

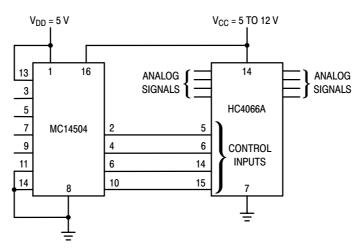


Figure 19. TTL/NMOS-to-CMOS Level Converter Analog Signal Peak-to-Peak Greater than 5 V (Also see HC4316A)

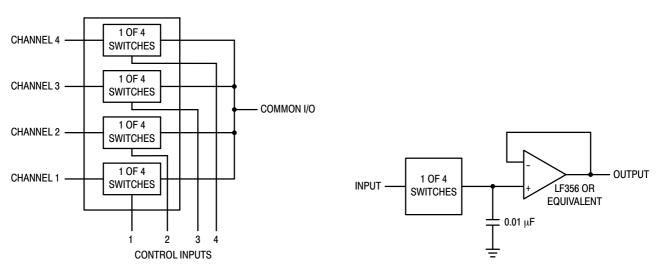
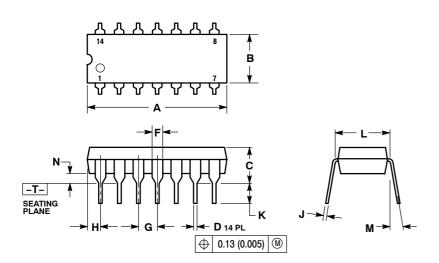


Figure 20. 4-Input Multiplexer

Figure 21. Sample/Hold Amplifier

#### **PACKAGE DIMENSIONS**

PDIP-14 **N SUFFIX** CASE 646-06 ISSUE P

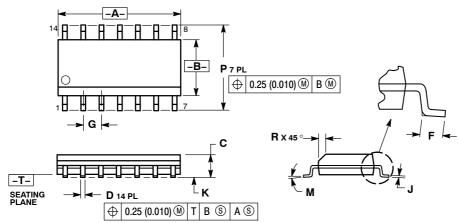


- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.715	0.770	18.16	19.56
В	0.240	0.260	6.10	6.60
С	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100 BSC		2.54	BSC
Н	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
М		10 °		10 °
N	0.015	0.039	0.38	1.01

#### **PACKAGE DIMENSIONS**

#### SOIC-14 **D SUFFIX** CASE 751A-03 **ISSUE J**



#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

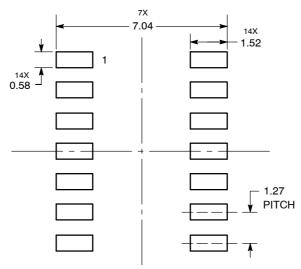
  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

  5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

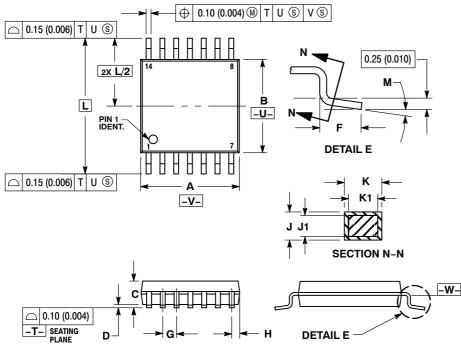
	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050	BSC
L	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
М	0 °	7°	0 °	7°
Р	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

#### **SOLDERING FOOTPRINT**



#### PACKAGE DIMENSIONS

#### TSSOP-14 **DT SUFFIX** CASE 948G-01 **ISSUE B**



14X **K** REF

#### NOTES:

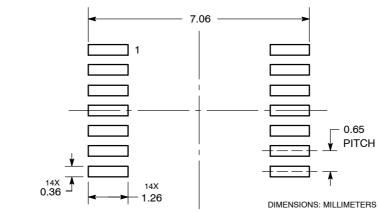
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
  MOLD FLASH OR GATE BURRS SHALL NOT
- EXCEED 0.15 (0.006) PER SIDE.

  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
  INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

  5. DIMENSION K DOES NOT INCLUDE
- DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		MILLIMET		INC	HES
DIM	MIN	MAX	MIN	MAX		
Α	4.90	5.10	0.193	0.200		
В	4.30	4.50	0.169	0.177		
С		1.20		0.047		
D	0.05	0.15	0.002	0.006		
F	0.50	0.75	0.020	0.030		
G	0.65	BSC	0.026	BSC		
Н	0.50	0.60	0.020	0.024		
J	0.09	0.20	0.004	0.008		
J1	0.09	0.16	0.004	0.006		
Κ	0.19	0.30	0.007	0.012		
K1	0.19	0.25	0.007	0.010		
L	6.40	BSC	0.252 BSC			
М	0 °	8 °	0 °	8 °		

#### **SOLDERING FOOTPRINT**



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